

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Weng-Jin Wu</td><td>12/02/2008</td></tr><tr><td>Hung-Jung Tu</td><td>12/02/2008</td></tr><tr><td>Ku-Feng Yang</td><td>12/02/2008</td></tr><tr><td>Jung-Chih Hu</td><td>12/30/2008</td></tr><tr><td>Wen-Chih Chiou</td><td>12/02/2008</td></tr></tbody></table>	Name	Execution Date	Weng-Jin Wu	12/02/2008	Hung-Jung Tu	12/02/2008	Ku-Feng Yang	12/02/2008	Jung-Chih Hu	12/30/2008	Wen-Chih Chiou	12/02/2008	
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Ku-Feng Yang	12/02/2008												
Jung-Chih Hu	12/30/2008												
Wen-Chih Chiou	12/02/2008												
RECEIVING PARTY DATA													
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.												
Street Address:	No. 8, Li-Hsin Rd. 6												
Internal Address:	Science-Based Industrial Park												
City:	Hsin-Chu												
State/Country:	TAIWAN												
Postal Code:	300-77 R.O.C.												
PROPERTY NUMBERS Total: 1													
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12329322</td></tr></tbody></table>	Property Type	Number	Application Number:	12329322									
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Application Number:	12329322												
CORRESPONDENCE DATA													
Fax Number:	(972)732-9218												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
Phone:	972-732-1001												
Email:	edwards@slater-matsil.com												
Correspondent Name:	Slater & Matsil, L.L.P.												
Address Line 1:	17950 Preston Road												
Address Line 2:	Suite 1000												
Address Line 4:	Dallas, TEXAS 75252												
ATTORNEY DOCKET NUMBER:	TSM08-0524												

CH \$40.00 12329322

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PATENT
REEL: 022267 FRAME: 0609

NAME OF SUBMITTER:

Kasey Edwards

Total Attachments: 3

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ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<i>Component Stacking Using Pre-Formed Adhesive Films</i>			
SIGNATURE OF INVENTOR AND NAME	<i>Weng-Jin Wu</i> Weng-Jin Wu	<i>Hung-Jung Tu</i> Hung-Jung Tu	<i>Ku-Feng Yang</i> Ku-Feng Yang	Jung-Chih Hu
DATE	<i>2008.12.2</i> <i>Weng-Jin Wu</i>	<i>2008.12.2</i>	<i>2008.12.2</i>	
RESIDENCE (City, County, State)	Hsin-Chu, Taiwan	Hualien, Taiwan	Dali City, Taiwan	Yangmei Township, Taiwan

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<i>Component Stacking Using Pre-Formed Adhesive Films</i>			
SIGNATURE OF INVENTOR AND NAME	Weng-Jin Wu	Hung-Jung Tu	Ku-Feng Yang	<i>Jung-chih Hu</i> Jung-Chih Hu
DATE				<i>Dec. 30, 2008</i>
RESIDENCE (City, County, State)	Hsin-Chu, Taiwan	Hualien, Taiwan	Dali City, Taiwan	Yangmei Township, Taiwan

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

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IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	<i>Component Stacking Using Pre-Formed Adhesive Films</i>			
SIGNATURE OF INVENTOR AND NAME	<i>Wen-Chih Chiou</i> Wen-Chih Chiou			
DATE	12/2 '08			
RESIDENCE (City, County, State)	Miaoli, Taiwan			